

IN THE SPECIFICATION:

Please amend paragraph [0027] as follows:

[0027] FIG. 2 illustrates a detailed view of semiconductor devices, namely interconnected functional die groups 13 and 15, the individual dice of each of which are operably coupled with an adjacent die interconnection circuit in accordance with an embodiment of the present invention. FIG. 2A illustrates a detail of interconnected functional die group 15 comprised of functional dice 18-24 which are illustrated as being arranged in a horizontally adjacent configuration. From previous probe testing, functional dice 18-24 were identified as being operational and further identified as being adjacently interconnectable, in accordance with an embodiment of the present invention. FIG. 2A illustrates an exemplary pinout configuration for each of functional dice 18-24 illustrated as being linearly configured arrays of bond pads 26-32. By way of example, and not limitation, arrays of bond pads 26-32 are illustrated as being comprised of a plurality of bond pads, for clarity's sake being illustrated as each only including four bond pads. Those of ordinary skill in the art appreciate that integrated circuits generally comprise an appreciable number of bond pads, and in the case of memory devices, include bond pads corresponding to address signals as well as other control signals including power, ground, and reference signals for individually accessing data storage elements. Interconnected functional die group 15 is further comprised of adjacent die interconnection segments 34-38 which are respectively formed between selected bond pads of arrays 26-32 to form a parallel interconnection scheme. Adjacent die interconnection ~~segments 34-38~~ are preferably formed as patterned conductors through the use of a subsequent wafer level processing technique.

Please amend paragraph [0038] as follows:

[0038] FIGs. 6 and 7 contemplate the deleterious effects associated with having a nonfunctional die within a larger assembly, namely the undesirable aberrational behavior or at least the undesirable additional capacitance associated with unnecessary circuitry attached to adjacent die ~~interconnect~~ interconnection segments. In FIG. 6, adjacent die interconnection

segments 118 and 120 bridge the coupling of functional die groups 106 and 108 through the coupling of the respective bond pads 122 and 124. However, bond pad 126 of nonfunctional die 110 is isolated through the process of open circuiting a nonfunctional die bond pad isolation conductive segment 128 through a manufacturing process such as laser ablation or through the use of an etching process through foregoing an interconnection processing step that generates an interconnect between bond pad 126 and conductive segment 128. Alternatively, FIG. 7 depicts the isolation of bond pad 126 from adjacent die interconnection segments 118 and 120 through the use of a gating or isolation device 130 which may be further controlled by an isolation control signal 132. Other forms of isolating bond pad 126 and the associated capacitance and deleterious effects associated therewith are also contemplated as within the scope of the present invention.